

Build up for Mindteck  
mind-11jun2k11-11690

0.0325	Copper plating layer 1		
0.0175	Copper foil layer 1	Signal	4 mil trace width, 8.3903 mil separation, 100 ohms differential 4 mil trace width, 40 mil separation, 109.43 ohms differential Target 120 ohms
	Prepreg 1 - 2		
0.0350	Copper foil layer 2	Plane	
	Core 2 - 3		
0.0350	Copper foil layer 3	Plane	
	Prepreg 3 - 4		
0.0175	Copper foil layer 4	Signal	4 mil trace width, 8.3903 mil separation, 100 ohms differential 4 mil trace width, 40 mil separation, 109.43 ohms differential Target 120 ohms
0.0325	Copper plating layer 4		
1.6000	Total PCB thickness in mm		

Disclaimer: This stack-up has assumptions regarding the copper area per layer, as well as prepreg distance & dielectric constants. An impedance tolerance of +/- 10% can only be achieved if we adjust the trace width & prepreg height to meet the impedance requirement after receipt of the gerber files.